GH6CD05B3A

4.8mm Thickness Resin Type Hologram Laser for CD Audio/Video CD Drive

■ Features

(1) With built-in 3V operation (3 to 5V), ×8 speed playback OPIC*

(2) Reducing variety of offset voltage (40% reduction) enables easy compatibility with CD-RW media.

(3) Insert frame structure enables easy mounting compared to conventional pin structure.

(4) Thin (4.8mm thickness) and compact package enables thin and compact pick-up design.

(5) With built-in beam splitter and diffraction grating

*OPIC : (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and a signal-processing circuit integrated onto a single chip.

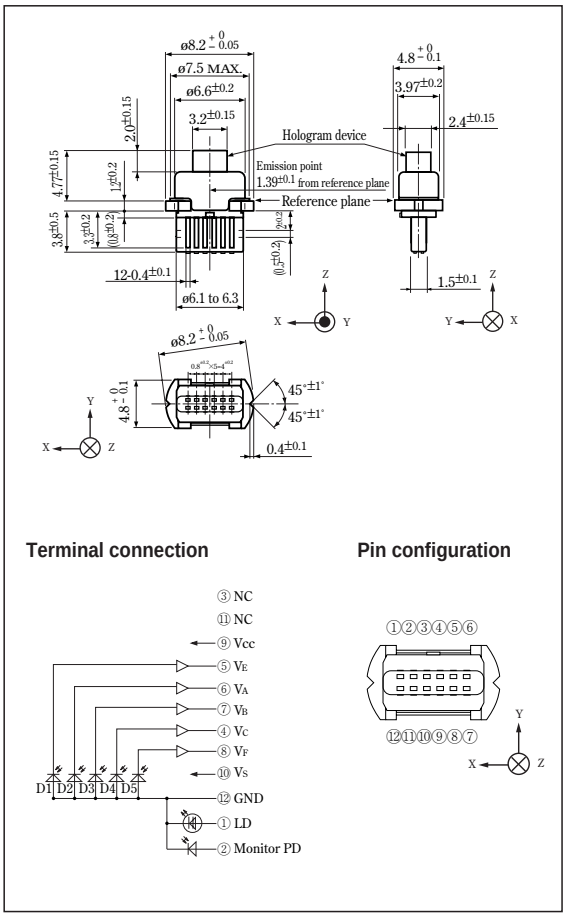
■ Applications

(1) CD audio players

(2) Video CD players

■ Outline Dimensions

(Unit : mm)



■ Absolute Maximum Ratings

(Tc=25°C)

Parameter		Symbol	Rating	Unit
*1 Optical power output		P_H	4.3	mW
Reverse voltage	Laser	V_R	2	V
	Monitor photodiode		30	V
OPIC supply voltage		V_{CC}	6	V
*2 Operating temperature		T_{opr}	-10 to +70	°C
*2 Storage temperature		T_{stg}	-40 to +85	°C
*3 Soldering temperature		T_{sold}	260	°C

*1 Output power from hologram laser, CW (Continuous Wave) drive

*2 Case temperature

*3 At the position of 1.6mm from the lead base (Within 5s)

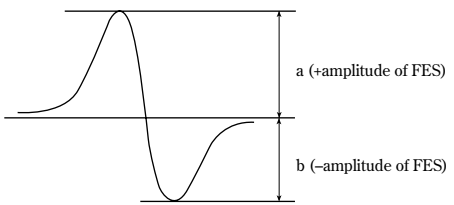
■ Electro-optical Characteristics

(V_{CC}=3V,V_S=1/2 V_{CC}, T_C=25°C)

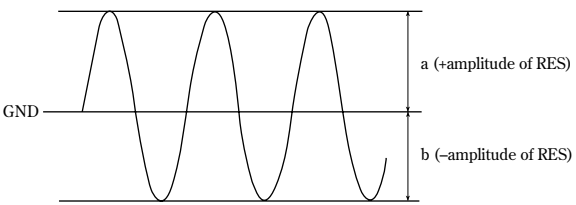
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
※1 Focal offset	DEF	V_{RF}=1.1V	-0.7	-	+0.7	µm
※2 Focal error symmetry	B_{FES}	V_{RF}=1.1V	-25	-	+25	%
※3 Radial error balance	B_{RES}	P_H=3.0mW	-25	-	+25	%
※4 RF output amplitude	V_{RF}	P_H=3.0mW	0.9	2.00	-	V
※5 FES output amplitude	V_{FES}	V_{RF}=1.1V	0.46	0.70	0.94	V
※6 RES output amplitude	V_{RES}	V_{RF}=1.1V	0.25	0.36	0.49	V
Threshold current	I_{th}	–	-	25	39	mA
Operating current	I_{op}	P_H=3.0mW	-	36	50	mA
Operating voltage	V_{op}	P_H=3.0mW	-	1.85	2.2	V
Wavelength	λ_p	P_H=3.0mW	770	780	795	nm
Output current	I_m	P_H=3.0mW, V_R=15V	0.06	0.32	0.60	mA
Differential efficiency	η_d	$\frac{2.0mW}{I(3.0mW)-I(1.0mW)}$	0.17	0.27	0.55	mW/mA

※1 Distance between FES=0 and jitter minimum point
At the condition of FES sensitivity = 20%/1µm

※2 (a–b) / (a+b)



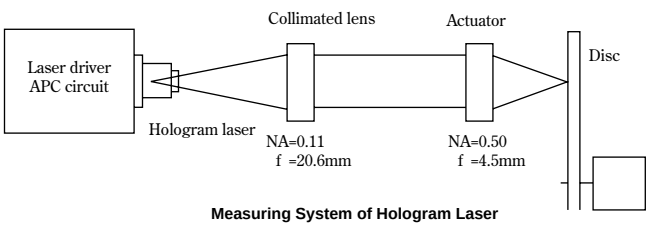
※3 $\frac{a-b}{2\times(a+b)}$



※4 Amplitude of $V_A+V_B+2V_C$ (focal servo ON, radial servo ON)

※5 $V_A–V_B$ (focal vibration)

※6 $V_E–V_F$ (focal servo ON, radial servo OFF)



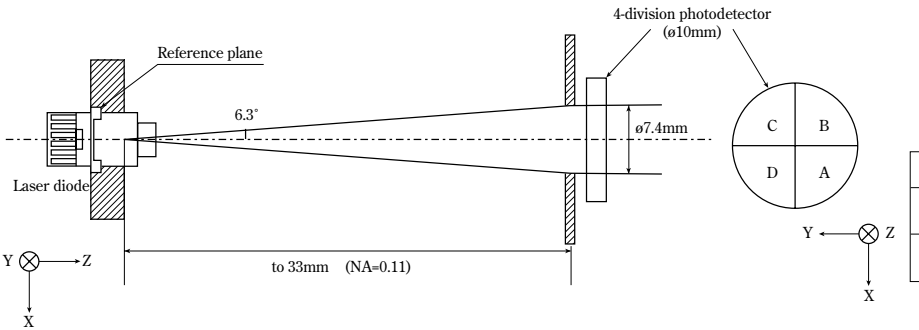
Measuring System of Hologram Laser

■ Electro-optical Characteristics of Laser Diode (Design Standard*)

(T_C=25°C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Emission characteristics	※1 Symmetry	Parallel	S//	Po=3mW, Into NA=0.11	-25	-	+25	%
		Perpendicular	S⊥		-15	-	+15	%
Misalignment position			Δx	–	-80	-	+80	μm
			Δy		-80	-	+80	μm
			Δz		-80	-	+80	μm
Z - position of emission point			z	–	-	1.39	-	mm
Interference pattern intensity			α	Po=3mW	-	-	0.99	-

※1 Measuring method of radiation symmetry



Parameter	Definition
S//	$\frac{(P_B + P_C) - (P_A + P_D)}{P_A + P_B + P_C + P_D}$
S⊥	$\frac{(P_A + P_B) - (P_C + P_D)}{P_A + P_B + P_C + P_D}$

P_X : Output of light detector X

■ Electrical Characteristics of Monitor Photodiode (Design Standard*)

(T_C=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
※2 Sensitivity	S	V_R=15V	-	0.11	-	mA/mW
Dark current	I_D		-	-	150	nA
Terminal capacitance	C_t		-	4.2	-	pF

※2 For hologram output power

■ Electro-optical Characteristics of OPIC for Signal Detection (Design Standard*)

(T_C=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	※3 Segment
Supply voltage	V_{CC}	-	2.8	-	5.5	V	
Supply current	I_{CC}	V_{CC}=3V	1.8	4.2	6.7	mA	
※4 Output offset voltage	V_{OD}	V_{CC}=3V No light	-11	0	+11	mV	V_A, V_B, V_C
			-13	0	+13	mV	V_E, V_F
Offset voltage difference	ΔV_{OD}		-11	0	+11	mV	V_A-V_B
			-13	0	+13	mV	V_E-V_F
Response frequency	f_{CF}	※5 V_{CC}=3V, -3dB R_L=10kΩ, C_L=10pF	12	18	-	MHz	V_A, V_B, V_C
	f_{CR}		1.2	1.8	-	MHz	V_E, V_F

※3 Applicable divisions correspond to output terminals.

D1	
D2	D4
D3	
D5	

Segment No. Output
D 1 ..... V_E
D 2 ..... V_A
D 3 ..... V_B
D 4 ..... V_C
D 5 ..... V_F

※4 Difference from Vs

※5 Output amplitude=0dB (input signal 100kHz) BW=10kHz

* These parameters are not guaranteed performance, but general specifications of each optical element which makes up a hologram laser.

• Please refer to the chapter "Handling Precautions"

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